

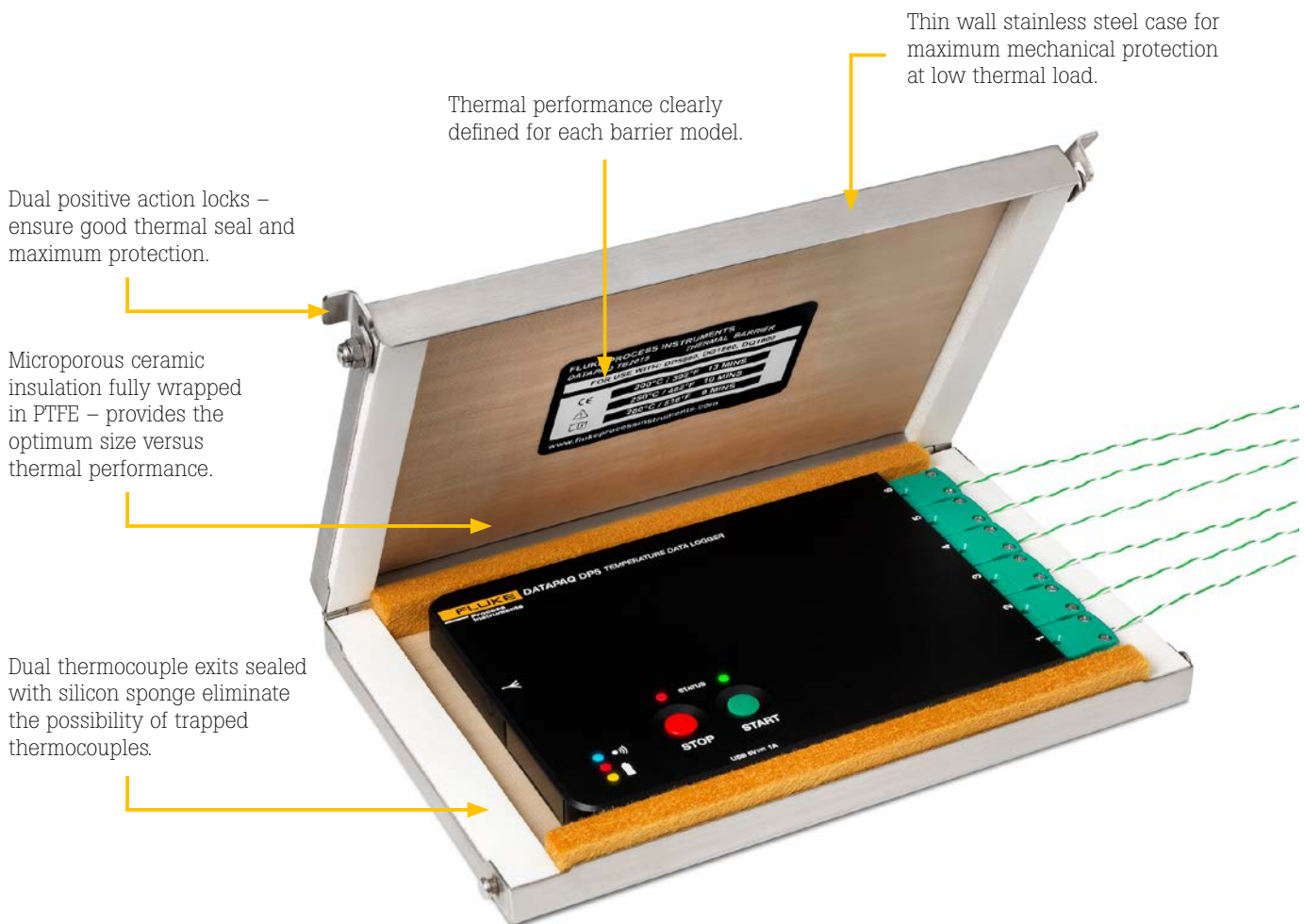
Technical Data

Thermal Barriers

for Datapaq DP5 6 & 12 channel

Our rugged stainless steel thermal barriers are incredibly lightweight and constructed using microporous ceramic insulation that ensures maximum protection and service life. Our most popular barrier weighs only 0.7 kg (1.6lb) and can survive temperatures of 300°C (572°F) for over eight minutes.

These thermal barriers routinely withstand the harshest industrial environments. They are made of the same insulation used in an airplane's 'black box' and are proven to protect your data logger run after run, day after day.



THERMAL BARRIERS SUITABLE FOR 6 CHANNEL DATA LOGGER – DP5660

TB2064 – Low height thermal barrier

A low height barrier for profiling ovens with very tight clearances. If rapid re-use is required or a longer than standard process is to be profiled, then consider TB2015 or TB2065.

Weight	0.6 kg (1.3 lb)		
Dimensions (H × W × L)	20 × 133 × 210 mm (0.8 × 5.2 × 8.3 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	9	8	6

TB2015 – Standard thermal barrier

The standard workhouse barrier used in thousands of facilities worldwide. If height is limited, consider the TB2064. If very frequent, heavy use is planned, consider the TB2065.

Weight	0.68 kg (1.5 lb)		
Dimensions (H × W × L)	25 × 133 × 210 mm (1.0 × 5.2 × 8.3 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	13	10	9

TB2065 – Long duration thermal barrier

Designed for longer duration and higher temperature processes. The choice when frequent profiling is needed and cool down time is limited.

Weight	0.68 kg (1.5 lb)		
Dimensions (H × W × L)	29 × 133 × 210 mm (1.1 × 5.2 × 8.3 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	13	11	10

THERMAL BARRIERS SUITABLE FOR 6 CHANNEL NARROW DATA LOGGER – DP5662

TB2020 – Low height narrow thermal barrier.

For profiling small products where oven width and height are limited.

Weight	0.5 kg (1.1 lb)		
Dimensions (H × W × L)	28 × 84 × 223 mm (1.1 × 3.3 × 8.8 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	10	8	7

TB2021 – Narrow thermal barrier

Narrow for limited width with enough insulation for rapid re-use. If height is limited, then consider the TB2020.

Weight	0.65 kg (1.4 lb)		
Dimensions (H × W × L)	35 × 84 × 223 mm (1.3 × 3.3 × 8.8 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	13	11	10



THERMAL BARRIERS SUITABLE FOR 6 CHANNEL SUPER SLIM DATA LOGGER – DP5661

TB2066 – Low height, slim thermal barrier

Created to profile very narrow and low height assemblies.

Weight	0.65 kg (1.4 lb)		
Dimensions (H × W × L)	20 × 87 × 328 mm (0.8 × 3.4 × 12.9 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	8	6	6

TB2067 – Standard slim thermal barrier

Standard height, yet slim for frequent profiling of narrow processes. If height is limited, consider the TB2066. If very heavy use is planned, consider the TB2068.

Weight	0.75 kg (1.7 lb)		
Dimensions (H × W × L)	25 × 87 × 328 mm (1.0 × 3.4 × 12.9 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	11	10	8

TB2068 – Long duration slim thermal barrier

For longer duration and higher temperature processes, or when frequent profiling is needed and cool down time is limited.

Weight	0.8 kg (1.8 lb)		
Dimensions (H × W × L)	29 × 87 × 328 mm (1.1 × 3.4 × 12.9 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	13	11	10

THERMAL BARRIERS SUITABLE FOR 12 CHANNEL DATA LOGGER – DP5612

TB2100 – Low height 12 channel thermal barrier

Designed primarily for use in convection or IR reflow soldering processes, where the process height is restricted and 12 thermocouple channels are required.

Weight	0.7 kg (1.5lb)		
Dimensions (H × W × L)	28 × 134 × 225 mm (1.1 × 5.3 × 8.9 in)		
Thermal Duration			
Temperature	200°C (392°F)	250°C (482°F)	280°C (536°F)
Duration (mins)	10	8	7

TB2101 – Standard 12 channel thermal barrier

Designed primarily for use in convection or IR reflow soldering processes.

Weight	0.8 kg (1.8lb)		
Dimensions (H × W × L)	35 × 134 × 225 mm (1.3 × 5.3 × 8.9 in)		
Thermal Duration			
Temperature	200°C (392 °F)	250°C (482 °F)	280°C (536 °F)
Duration (mins)	13	11	10



The Fluke Process Instruments Guarantee

Each Fluke Process Instruments system is supported with a full one year warranty.

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Worldwide Service

Fluke Process Instruments offers services, including repair and calibration. For more information, contact your local office.

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Specifications subject to change without notice.

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